



Title of Change:	Assembly Site and Material Change for Translator in Micro8 Package.
Proposed first ship date:	16 April 2019
Contact information:	Contact your local ON Semiconductor Sales Office or < logic.fpcn@onsemi.com >
Samples:	Contact your local ON Semiconductor Sales Office or < PCN.samples@onsemi.com > Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or < Phine.Guevarra@onsemi.com >.
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact < PCN.Support@onsemi.com >
Change Part Identification:	Affected product will be marked with new plant code.
Change Category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input checked="" type="checkbox"/> Test Change <input type="checkbox"/> Other _____

Change Sub-Category(s):

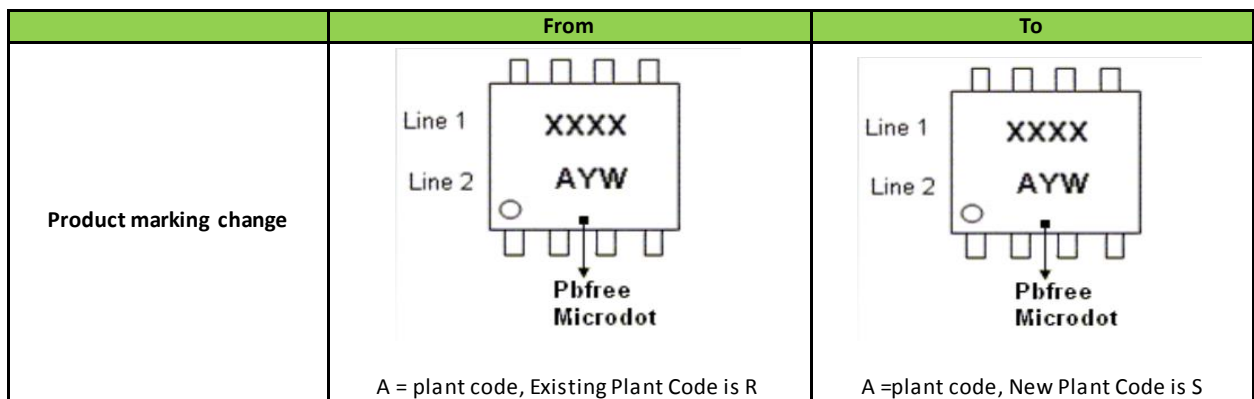
<input type="checkbox"/> Manufacturing Site Addition	<input checked="" type="checkbox"/> Material Change	<input type="checkbox"/> Datasheet/Product Doc change
<input checked="" type="checkbox"/> Manufacturing Site Transfer	<input type="checkbox"/> Product specific change	<input checked="" type="checkbox"/> Shipping/Packaging/Marking
<input checked="" type="checkbox"/> Manufacturing Process Change	<input type="checkbox"/> Other: _____	

Sites Affected:	ON Semiconductor Sites: ON SBN, Malaysia	External Foundry/Subcon Sites: Subcon Thailand
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Description and Purpose:

Qualify new assembly and test site to increase the back end capacity.

Material to be changed	Before change (existing flow)	After 90 day notification (new flow)
Assy Site	ON Malaysia	Subcon Thailand
Mold Compound	G600FB/G700LS	G600
Lead Frame	Ag Plated LF	PPF LF
Die Attach	Epoxy CRM1084P	Epoxy QMI519
Plating	100% Tin	Pre plated





Reliability Data Summary:

QV DEVICE NAME: NLVSV2T244DMR2G

RMS: S46916

PACKAGE: Micro 8

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta= 125°C	2016 hrs	0/80
HTSL	JESD22-A103	Ta= 150°C	2016 hrs	0/80
TC	JESD22-A104	Ta= -65°C to + 150°C	1000 cyc	0/80
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/80
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/80
PC	J-STD-020 JESD-A113	MSL 1 @ 260°C		0/240
RSH	JESD22- B106	Ta = 265C, 10 sec		0/15
SD	JSTD002	Ta = 245C, 10 sec		0/ 10

Electrical Characteristic Summary:

No impact on electrical characteristics.

List of Affected Parts:

Part Number	Qualification Vehicle
NLSX4373DMR2G	NLVSV2T244DMR2G
NLSV2T244DMR2G	
NLSX3012DMR2G	

Appendix A: Changed Products

Product	Customer Part Number	Qualification Vehicle
NLSV2T244DMR2G		NLVSV2T244DMR2G
NLSX3012DMR2G		NLVSV2T244DMR2G
NLSX4373DMR2G		NLVSV2T244DMR2G